01-25-2005



PATENTS ONLY

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Please record the amount of solution document or copy thereof.

1. Name of party or parties conveying an interest:	2. Name and address of party or parties receiving an interest:
Kwan-Ju KOH	Name: DongbuAnam Semiconductor, Inc. a Korean corporation 891-10 Daechi-dong, Kangnam-ku, Seoul 135-523, Korea
3. Description of the interest conveyed:	Other:
X Assignment	
Merger	
Change of NameSecurity Agreement	
Execution Date: December 28, 2004	
4. Application number(s) or patent number(s). Additional sheet attached? YES NO_X	If the document is being filed together with a new application, the execution date of the application is:
A. Patent Application no.(s): Not yet assigned filed December 30, 2004	B. Patent no.(s):
5. Name and address of party to whom correspondence concerning this cover sheet should be mailed:	6. Number of applications and/or patents identified on this cover sheet: 1
Name: James A. Flight	7. Amount of fee enclosed or authorized to be
Reg. No. 37,622	charged:
HANLEY, FLIGHT & ZIMMERMAN, LLC	\$40.00
Street Address: 20 North Wacker Drive	
Suite 4220	8. Any additional required fee may be charged, or any overpayment credited to our deposit
City: Chicago	account: 50-2455
State: Illinois Zin: 60606	account. 50-2455
Zip: 60606	

9. To the best of my knowledge and belief, the information contained on this cover sheet is true and correct and any copy submitted is a true copy of the original document.

Date: December 30, 200 4

James A. Flight

Registration No. 37,622

Total number of pages including cover sheet, attachments, and document: 3

01/06/2005 STEUMEL1 00000015 11027044 01 FC:8021 40.00 OP

> PATENT REEL: 016159 FRAME: 0185

## ASSIGNMENT

Serial No:

Filed. December 30, 2004

Title: SEMICONDUCTOR DEVICES AND METHODS OF MANUFACTURING THE SAME

For good and valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assigns to **DongbuAnam Semiconductor** Inc. of 891-10. Daechi-dong. Kangnam-ku. Seoul. 135-523. Korea (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, and in said application and any and all other applications, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States, which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned hereby authorizes and requests the attorneys of record in said application to insert in this assignment the execution date and/or filing date and serial number of said application when officially known.

The undersigned warrants himself to be the owner of the interest herein assigned and to have the right to make this assignment and further warrants that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agrees, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application, that said assignee, its successors or assigns, may deem necessary or expedient, and for said consideration the undersigned further agrees upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent, and vest all rights therein hereby conveyed in said assignee, its

PATENT REEL: 016159 FRAME: 0186 successors and assigns, whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

Date:

December 28, 2004

Signature

KOH kwan Ju

Name \* \* \* \* \*

> PATENT REEL: 016159 FRAME: 0187

**RECORDED: 12/30/2004**